

# SILVER/PLATINUM ON ALUMINUM NITRIDE

Thick film silver/platinum on aluminum nitride provides excellent wire bond adhesion, electrical conductivity and leach resistance.

Typical Properties of Silver/Platinum Metallization System		
<b>Resistivity</b>		4.0 mΩ/sq
<b>Printing Resolution</b>	(line/space)	125 μm/125 μm
<b>Wettability</b>	(5 sec dip, 50 In/50 Pb solder)	90 – 100%
<b>Wire Bond Adhesion</b>		
Initial	(Au wire, 4.0 mil dia)	58 g
Aged 24 h at 300°C	(Au wire, 4.0 mil dia)	55 g
<b>Adhesion*</b>		≥68.9 MPa

\*Pull testing with 3.0 mm square pads and epoxy adhesive aluminum studs.

Sienna's technical team is ready to help you implement Aluminum Nitride in your next generation of products.

**Contact us for applications assistance and fast prototyping.**

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